



PATENT APPLICATION

**RESPONSE UNDER 37 CFR §1.116
EXPEDITED PROCEDURE
TECHNOLOGY CENTER ART UNIT 2825**

#2310
JUN 2003
326163

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Akira SATO

Application No.: 09/424,500

Filed: February 22, 2000

Group Art Unit: 2825

Examiner: G. Lee

Docket No.: 104788

For: METHOD OF MANUFACTURING SEMICONDUCTOR DEVICE, MOLDING DEVICE FOR SEMICONDUCTOR DEVICE, AND SEMICONDUCTOR DEVICE

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AMENDMENT AFTER FINAL REJECTION UNDER 37 CFR §1.116

Director of the U.S. Patent and Trademark Office
Washington, D.C. 20231

Sir:

In reply to the November 19, 2003 Office Action, the period for reply being extended by the attached Petition for Extension of Time, please amend the above-identified application as follows:

IN THE CLAIMS:

Please replace claims 1, 12 and 15 as follows:

1. (Thrice Amended) A method of manufacturing a semiconductor device comprising:

placing a semiconductor assembly in which a semiconductor chip is secured to a die pad of a lead frame in a cavity of a mold;

applying a pressure to the semiconductor assembly by at least one support pin so as to cause a stress in the lead frame;